Overview

HP EliteBook x360 830 G8 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Web cam LED
- 3. HD and IR Camera (Optional)
- 4. Camera Shutter
- 5. IR Camera LEDs (Optional)
- 6. Ambient Light Sensor

- 7. Glass Clickpad
- 8. Smartcard Reader (Optional)
- 9. Audio Combo Jack
- 10. Super Speed USB Type-A 5Gbps signaling rate (1 charging)
- 11. Super Speed USB Type-A 5Gbps signaling rate (1 charging)
- 12. Nano Security Lock Slot (Lock sold separately)



Overview



1. Power Button Key

- 2. Power Connector
- 3. HDMI 2.0b Port (Cable not included)
- 4. Thunderbolt™ 4 with USB4™ Type-C® 40Gbps signaling rate ¹

Right

- 5. Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate ¹
- 6. SIM Card Slot (Optional)
- 7. Touch fingerprint Sensor (Select models)

1. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.



Overview

At a Glance

- Premium ultraslim design with precision-crafted machined CNC aluminum x360 design with four usage modes that is 0.71 inches (1.79 cm) thin with a starting weight of 2.98 lbs. (1.35 Kg)
- 11th Generation Intel® Core™ i5, i7 Processors
- Preinstalled with Windows 10 versions or FreeDOS 3.0
- Find your missing laptop even when it's turned off using the optional Tile™ feature and app
- · Optional ultrabright, anti-glare touch displays with ambient light sensor
- Choice of displays:
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Low Power
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 400 nits, 72% NTSC with Low Power
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit BrightView touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View Reflect Integrated Privacy Screen
 - 33.8 cm (13.3") diagonal FHD IPS LED-backlit Anti-Glare glass touch with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HP Sure View Reflect Integrated Privacy Screen
- Enterprise grade security with HP Sure Sense, HP Sure Start Gen7, HP Privacy Camera, HP Sure View Reflect, HP Sure Run Gen4, HP Sure Recover Gen4 with Embedded Reimaging, HP Sure Click, SmartCard Reader and Touch Fingerprint reader
- An optional HP Rechargeable Active Pen 31 with Magnetic Attach and 4096 Levels of pressure
- Connectivity with optional CAT20 5G/ WWAN, and Thunderbolt™ Docking (Dock sold separately)
- Choice of solid state drives up to 2 TB and DDR4 memory up to 32 GB
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles3
- Featuring redesigned quiet HP Keyboard with the HP Programmable key and backlit options
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360-degree mic pick-up allows everyone to clearly hear and be heard
- Long battery life up to TBD hours and TBD minutes
- Undergoes MIL-STD 810H tests²
- Instant on/instant off with Modern Connected Standby
- Intel® Iris® Xe Graphics
 - 1. HP Rechargeable Active Pen 3 sold separately.
 - 2. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAME

HP EliteBook x360 830 G8 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64 – HP recommends Windows 10 Pro for business ¹

Windows 10 Pro 64 (National Academic License)²

Windows 10 Home 64 1

Windows 10 Home Single Language 64 1

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) 1

Windows 10 Enterprise 64 (Web Support)1

FreeDOS

- 1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply, and additional requirements may apply over time for updates. See https://www.windows.com/.

PROCESSORS

Intel® Core™ i7-1165G7 with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) 3,45,6

Intel® Core™ i7-1185G7 (up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores), supports Intel® vPro® Technology ^{3,4,5,6}

Intel® Core™ i5-1135G7 with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 2 cores) 3,45,6

Intel® Core™ i5-1145G7 (up to 4.4 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores), supports Intel® vPro® Technology ^{3,4,5,6}

Processor Family

11th Generation Intel® Core™ i7 processor (i7-1165G7) 6

11th Generation Intel® Core™ i5 processor (i5-1135G7) 6

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode. 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See
- www.intel.com/technology/turboboost for more information.
 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET



Technical Specifications

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics7

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.38

- 7. Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.
- 8. HDMI cable sold separately.

DISPLAY

Touch

33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen 250 nits, 45% NTSC with HD camera (1920 x 1080)^{9,10,11}

33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080) 9,10,11

33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen, 400 nits, 72% NTSC with Low Power, Ambient Light Sensor and HD+IR camera (1920 x 1080) 9,10,11

33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen, 400 nits, 72% NTSC with Low Power, Ambient Light Sensor and HD+IR camera for WWAN (1920 \times 1080) 9,10,11

33.8 cm (13.3") diagonal FHD IPS Anti-Glare WLED-backlit bent touch screen 400 nits, 72% NTSC with Low Power, Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080) 9,10,11

HP Sure View Reflect Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen, 1000 nits. 72% NTSC with Ambient Light Sensor and HD+IR camera (1920 x 1080) 9,10,11

HP Sure View Reflect Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS BrightView WLED-backlit bent touch screen, 1000 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080) 9,10,11

HP Sure View Reflect Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS Anti-Glare WLED-backlit bent touch screen, 1000 nits. 72% NTSC with Ambient Light Sensor and HD+IR camera (1920 x 1080) 9.10,11,12

HP Sure View Reflect Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS Anti-Glare WLED-backlit bent touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080) 9,10,11,12

HP Sure View Reflect Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD IPS Anti-Glare WLED-backlit bent touch screen, 400 nits, 72% NTSC with Low Power, Ambient Light Sensor and HD+IR camera for WWAN (1920 x 1080) 9,10,11,12

HDMI 2.0¹³

Support resolution up to 4K @60 Hz





Technical Specifications

- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. Actual brightness will be lower with touchscreen or Sure View.
- 12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.
- 13. HDMI cable sold separately.

Docking station model (Sold separately)	Total number of supported displays (incl. the notebook) display)	Max resolutions supported for DP 1.4 hosts with DSC	Dock Connectors	Technical limitations / additional information For more details refer to HP Dock QuickSpecs http://h20195.www2.hp.com/v2/GetDocume nt.aspx?docname=c04168358 All information below applies to platforms running DP 1.4 with DSC
HP Thunderbolt Dock G2	Max number of displays = 4	Dual 8K@ 60Hz in high res mode	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	Max displays = 4 with max resolution of 5K@ 30Hz running Thunderbolt host Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode The highest resolution for dual displays running a non-Thunderbolt host in Multifunction mode is one 5K dual cable (using both DP ports) + one 4K on USB-C DP port
HP USB-C Dock G5	3	Dual 5K@ 30Hz + 1 4K UHD (multi- function mode)	1xHDMI, 2xDP	Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in Multi-function mode Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode The highest resolution for running a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + one 4K on HDMI port



Technical Specifications

HP USB-C/A Universal Dock G2	3	Triple 4K UHD@ 60Hz	1xHDMI, 2xDP	In High Resolution, mode the max available is one display. This dock's best use case is triple display. The best resolution for dual display is two 4K UHD@ 60Hz Highest triple displays resolution available is three 4KUHD @60Hz using both DP and 1 HDMI port. Best single display is with High Resolution mode using HDMI port.
HP USB-C Travel Dock G2	1	Single 4K@ 30 Hz 4960 x 2160 (via HDMI)	1xHDMI, 1xVGA	Single external display using either HDMI or VGA

STORAGE AND DRIVES

Primary M.2 Storage 128 GB PCIe® Gen3x2 NVMe™ M.2 SSD TLC¹⁴

256 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC¹⁴
512 GB PCIe® Gen3x4 NVMe™ M.2 SSD TLC¹⁴
1 TB PCIe® Gen3x4 NVMe™ M.2 SSD TLC¹⁴
2 TB PCIe® Gen3x4 NVMe™ M.2 SSD TLC¹⁴
256 GB PCIe® NVMe™ Value M.2 SSD¹⁴
512 GB PCIe® NVMe™ Value M.2 SSD¹⁴

512 GB PCle®Gen 3x4 NVMe™ M.2 SED TLC OPAL2¹⁴ 256 GB PCle® Gen3x4 NVMe™ M.2 SED TLC OPAL2¹⁴

512 Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10^{14,15}

14. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

15. Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.



Technical Specifications

MEMORY

Maximum Memory 32GB DDR4-3200 SDRAM ¹⁶

Memory

32 GB DDR4-3200 SDRAM ¹⁶ 16 GB DDR4-3200 SDRAM ¹⁶ 8 GB DDR4-3200 SDRAM ¹⁶

Memory Slots Memory soldered down

DDR4 SODIMM, System runs at: 3200 Supports Dual Channel Memory

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AX201 802.11a/b/g/n/ac (2x2) Wi-Fi 6 and Bluetooth® 5 Combo, vPro® 17,18 Intel® Dual Band Wireless-AX201 802.11a/b/g/n/ac (2x2) Wi-Fi 6 and Bluetooth® 5 Combo, non-vPro® 17

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 9 ¹⁹
Qualcomm® Snapdragon™ X55 5G Module Cat 20²⁰

Near Field Communication (NFC) module ²² NPC300 Near Field Communication module

Miracast

Native Miracast Support 21

- 17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.
- 18. For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html
- 19. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.
- 20. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.



Technical Specifications

- 21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 22. Sold separately or as an optional feature.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers World-facing 3rd mic

Camera

720p HD camera ^{9,22} 720p HD+IR camera ^{9,22}

Sensor

ALS (ambient light sensor) Hall Sensor HP Tamper Lock 54

- 9. FHD/HD content required to view FHD/HD images.
- 22. Sold separately or as an optional feature.
- 54. HP Tamper Lock must be enabled by the customer or your administrator.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Non-Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys Privacy

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center (Programmable Key)

Print Screen

Power Button (with LED)

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen6 ²³
HP Drive Lock & Automatic Drive Lock
BIOS Update via Network
Power On Authentication
HP Secure Erase ²⁴
Absolute Persistence Module ²⁵
HP LAN-Wireless Protection
Pre-boot Authentication

Software

HP Connection Optimizer ²⁶
HP Hotkey Support
myHP
HP Support Assistant ²⁷
HP QuickDrop
HP Noise Cancellation Software



Technical Specifications

Touchpoint Customizer for Commercial

HP Notifications

HP Privacy Settings

HP Wireless Button Driver

HP Power Manager

HP WorkWell

Tile App 28

HP Programmable Key

HP PC Hardware Diagnostics Windows

Buy Microsoft Office (Sold separately)

Manageability Features

HP Driver Packs (download) 29

HP Manageability Integration Kit Gen4 (download) 30

HP System Software Manager (SSM) (download)

HP BIOS Config Utility (BCU) (download)

HP Client Catalog (download)

HP Client Management Script Library (download)

HP Image Assistant (download)

Client Security Software

HP Client Security Manager Gen7 55 Windows Defender 31

Security Management

Pre-boot Authentication

USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

HP Fingerprint Sensor 32

Support for chassis padlocks and cable lock devices

HP Pro Security Edition (Select models) 33

HP Sure Click 34

HP Sure Sense 35

HP Sure Start Gen7 36

HP Sure Run Gen449

HP Sure Recover Gen450

HP Sure Admin 37

HP Sure View 38

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2

Certified) 39

Secured-core PC capable52

23. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.

24. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

25. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit:

https://www.absolute.com/about/legal/agreements/absolute/

26. HP Connection Optimizer requires Windows 10.

27. HP Support Assistant requires Windows and Internet access.



Technical Specifications

28. Tile is an optional feature that must be configured at the factory and requires Windows 10. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.

- 29. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 30. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 31. Windows Defender Opt in and internet connection required for updates.
- 32. HP Fingerprint sensor is an optional feature that must be configured at purchase.
- 33. HP Pro Security Edition is available preloaded on select HP PCs and includes HP Sure Click Pro and

HP Sure Sense Pro. 3-year license required. The HP Pro Security Edition software is licensed under the license terms of the HP End User License Agreement (EULA) that can be found at:

https://h30670.www3.hp.com/ecommerce/common/disclaimer.do#EN_US as modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for thirty-six (36) months thereafter ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support." HP Pro Security Edition is optimized for the SMB environment and ships pre-configured - manageability is optional. The HP Pro Security Edition supports a limited tool set that can be used by the HP Manageability Integration Kit which can be downloaded from http://www.hp.com/go/clientmanagement.

- 34. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details
- 35. HP Sure Sense is available on select HP PCs and is not available with Windows 10 Home.
- 36. HP Sure Start Gen7 is available on select HP PCs.
- 37. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- 38. HP Sure View Reflect integrated privacy screen is designed to function in landscape orientation.
- 39. Firmware TPM is version 2.0.
- 49. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
- 50. HP Sure Run Gen4 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
- 52. Secured-core PC capable requires an Intel vPro or AMD Ryzen Pro processor. Requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.
- 55. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.

SMART CARD READER

Smart Card Reader (Optional)

Model number FIPS 201 Compliant

Alcor AU9560

Yes

POWER

Power Supply



Technical Specifications

HP Smart 45 W External AC power adapter ⁴⁰
HP Smart 45 W External AC power adapter, 2-prong (Japan only)⁴⁰
HP Smart 65 W External AC power adapter ⁴⁰
HP Smart 65 W EM External AC power adapter ⁴⁰
HP 65 W Slim USB Type-C AC power adapter ⁴⁰
HP 65 W USB Type-C AC power adapter

Primary Battery

HP Long Life 3-cell, 53 Wh Li-ion 41,51

Power Cord

2-wire plug - 1m (Japan only) 3-wire plug - 1m Premium - 1m

Battery life

Up to TBD hours and TBD minutes⁴²

Battery Weight 210g±10g

- 40. Availability may vary by country.
- 41. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 42. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.
- 51. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.



Technical Specifications

WEIGHTS & DIMENSIONS

Product Weight

Touch Starting at 2.98 lb (1.35 kg) ⁴³

Product Dimensions

12.1 x 8.07 x 0.71 in 30.75 x 20.5 x 1.79 cm

43. Weight will vary by configuration.

PORTS/SLOTS

2 Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate ⁵³

2 Super Speed USB Type-A 5Gbps signaling rate (1 charging)

1 HDMI 2.0b 44

1 Headphone/microphone combo

1 4.5 mm AC Adapter Port

1 nano SIM card slot⁴⁵

1 Smartcard reader (Optional)

1 Nano Security Lock Slot (Lock sold separately)

44. HDMI cable sold separately

45. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug.

53. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4

SERVICE AND SUPPORT

1-year and 3-year limited warranties and 90 day software limited warranty options depending on country.

Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/

for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 46

46. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage



19.5V

Technical Specifications

Average Operating Power 1.825W **Integrated graphics** Yes N/A **Discrete Graphics**

Max Operating Power UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C)

Non-operating 41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m) **Non-operating** -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard Certifications

> UL YES **CSA** YES **FCC Compliance** YES

Select models⁴⁷ **ENERGY STAR®**

EPEAT® EPEAT 2019 Gold in United States⁴⁸

ICES YES Australia / YES YES **NZ A-Tick Compliance** CCC YES **Japan VCCI Compliance** YES

YES KC **BSMI** YES **CE Marking Compliance** YES **BNCI or BELUS** YES CIT YES **GOST** YES Saudi Arabian Compliance YES

(ICCP)

SABS YES



Technical Specifications

47. Configurations of the HP EliteBook x360 830 G8 Notebook PC that are ENERGY STAR® certified are identified as HP EliteBook x360 830 G8 Notebook ENERGY STAR on HP websites and on http://www.energystar.gov.

48. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or Sure View.

LCD 13.3 inch Diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% cg 250nits eDP 1.2 w/o PSR

LCD 13.3 inch Diagonal FHD Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max) (FPC folding included)

Active Area 293.76 x 165.24 mm (typ.)

Weight 260 g (max)
Diagonal Size 13.3 inch

Thickness 3.0 mm/ 5.0 mm (PCB) (max)

InterfaceeDP 1.2 (2lane)Surface TreatmentBrightView Glass

Touch Enabled Yes

Contrast Ratio 600:1 (typ.)
Refresh Rate 60 Hz

Brightness 250 nits (Panel Only)¹ Pixel Resolution 1920 x 1080 (FHD)

Format RGB

Backlight LED

Color Gamut Coverage NTSC 45%

Color Depth 6 bits

Viewing Angle UWVA 85/85/85



LCD 13.3 inch Diagonal FHD Outline Dimensions (W x H x D) (1920 x 1080) Anti-Glare Active Area 299.06 x 176.54 mm (max) (FPC folding included) 293.76 x 165.24 mm (typ.)

Technical Specifications

WLED UWVA sRGB 100% cg Weight 400nits eDP 1.4+PSR2 bent Diagon

Weight 175 g (max)
Diagonal Size 13.3 inch

Thickness2.0 mm / 3.8 mm (PCB) (max)InterfaceeDP 1.4 w/ PSRII (2 lane)

Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 1500:1(typ.)
Refresh Rate 60Hz

Brightness 400 nits (Panel Only) ¹ **Pixel Resolution** 1920 x 1080 (FHD)

Format RGB Backlight LED

Color Gamut Coverage sRGB 100% (NTSC 72%)

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

LCD 13.3-in Diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% cg 1000nits eDP 1.4+PSR HP

Sure View Reflect

Outline Dimensions (W x H x D) 299.06 x 176.54 mm (max)

Active Area 293.76 x 165.24 mm (typ.)

 Weight
 220 g (max)

 Diagonal Size
 13.3 inch

 Thickness
 3.9 mm (max)

Interface eDP 1.4 + PSR (4 lane)

Surface Treatment Anti-glare glass

Touch Enabled Yes

Contrast Ratio1500:1 (typ.)Refresh Rate60 HzBrightness1000 nits1

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 72%
Color Depth 8bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch FHD (1920x1080) Anti-Glare

Outline Dimensions (W x H x D)
Active Area

299.06 x 176.54 mm (max) (FPC folding included)

293.76 x 165.24 mm (typ.)



Technical Specifications

WLED UWVA sRGB 100percent cg 400nits eDP 1.4+PSR2 bent Weight 175 g (max)
Diagonal Size 13.3 inch

Thickness 2.0 mm / 3.8 mm (PCB) (max) Interface eDP 1.4 w/ PSRII (2 lane)

Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 1500:1(typ.)
Refresh Rate 60Hz

Brightness 400 nits (Panel Only) ¹ **Pixel Resolution** 1920 x 1080 (FHD)

Format RGB Backlight LED

Color Gamut Coverage sRGB 100% (NTSC 72%)

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 13.3-in FHD (1920x1080) Anti-Glare WLED UWVA 72percent cg 1000nits eDP 1.4+PSR HP Sure View Reflect Outline Dimensions (W \times H \times D)

Active Area

299.06 x 176.54 mm (max) 293.76 x 165.24 mm (typ.)

Weight 220 g (max)

Diagonal Size 13.3 inch

Thickness 3.9 mm (max)

Interface eDP 1.4 + PSR (4 lane)
Surface Treatment Anti-glare glass

Touch Enabled Yes

Contrast Ratio 1500:1 (typ.)
Refresh Rate 60 Hz
Brightness 1000 nits¹

brightness 1000 filts

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 72%
Color Depth 8bits

Viewing Angle UWVA 85/85/85



Technical Specifications

STORAGE AND DRIVES

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 128GB 2280 PCIe-3x2 Three Layer Cell Form Factor M.2 2280
Capacity 128GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

Interface PCIe NVMe Gen3X4 or Gen3X2

Maximum Sequential ReadUp To 2047 MB/sMaximum Sequential WriteUp To 1200 MB/sLogical Blocks250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 256GB 2280 PCIe-3x4 Form Fac NVMe Self Encrypted OPAL2 Capacity TLC

Form Factor M.2 2280
Capacity 256GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfaceATA-8, SATA 3.0Maximum Sequential ReadUp To 3500 MB/sMaximum Sequential WriteUp To 2200 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

SSD 256GB 2280 PCIe NVMe Form Factor
Value Solid State Drive Capacity

Form Factor M.2 2280
Capacity 256GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 1700 MB/s
Maximum Sequential Write Up To 600 MB/s
Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2



Technical Specifications

SSD 256GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 2800 ~ 3500 MB/s

 Maximum Sequential Write
 1400 ~ 2200 MB/s

 Logical Blocks
 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

SSD 512GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2600 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512GB 2280 PCIe-3x4 Form Fac NVMe Self Encrypted OPAL2 Capacity TLC

Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 2900 MB/sMaximum Sequential WriteUp To 1400 MB/sLogical Blocks1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512GB 2280 PCIe NVMe Form Factor Value

Form Factor M.2 2280
Capacity 512GB
NAND Type TLC



Technical Specifications

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up to 1700 MB/s
Maximum Sequential Write Up to 1500 MB/s
Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 1TB 2280 PCIe-3x4 NVMe TLC SS Form Factor M.2 2280
Capacity 1TB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 3480 MB/sMaximum Sequential WriteUp to 2800 MB/sLogical Blocks2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 512GB 2280 PCIe-3x2x2 NVMe+SSD 32GB 3D Xpoint Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp to 2400 MB/sMaximum Sequential WriteUp to 1300 MB/sLogical Blocks1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

SSD 2TB 2280 PCIe-3x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 2TB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 3500 MB/sMaximum Sequential WriteUp To 3000MB/s



Technical Specifications

Logical Blocks

Operating Temperature

Features

3,907,029,168

32° to 158°F (0° to 70°C) [ambient temp]

ATA Security; TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Intel® Wi-Fi® 6 AX201 Wireless LAN
+ Bluetooth® 5 Standards IEEE 802.11b
(802.11ax 2x2,
vPro TM, supporting
gigabitdata rate5)
vPro®1 IEEE 802.11d
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11d
IEEE 802.11d
IEEE 802.11d

IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability Features Wi-Fi 6 technology

Frequency Band •802.11b/g/n/ax

2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz

5.825 - 5.850 GHz"802.11b/g/n/ax

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac :MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
 802.11ax MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ •IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •WPA3 certification •IEEE 802.11i

•WAPI

Network Ad-hoc (Peer to Peer)

Architecture Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² •802.11g: +17.5dBm minimum

•802.11a : +18.5dBm minimum

•802.11n HT20(2.4GHz): +15.5dBm minimum •802.11n HT40(2.4GHz): +14.5dBm minimum •802.11n HT20(5GHz): +15.5dBm minimum •802.11n HT40(5GHz): +14.5dBm minimum •802.11ac VHT80(5GHz): +11.5dBm minimum •802.11ac VHT160(5GHz): +10dBm minimum •802.11ax VHT160(5GHz): +10dBm minimum



Technical Specifications

Power Consumption • Transmit mode: 2.0 W

•Receive mode:1.6 W

Idle mode (PSP180 mW(WLAN Associated)
Idle mode:50 mW(WLAN unassociated)
Connected Standby/Modern Standby: 10mW

•Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ •802.11b, 1Mbps: 93.5dBm maximum

•802.11b, 11Mbps: 84dBm maximum •802.11a/g, 6Mbps: -86dBm maximum •802.11a/g, 54Mbps: 72dBm maximum •802.11n, MCS07: 67dBm maximum •802.11n, MCS15: 64dBm maximum •802.11ac, MCS0: 84dBm maximum •802.11ac, MCS9: 59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support

WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (–10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth 4.0/4.1/4.2/5.0/5.1 Compliant

Specification

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric

(3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW



Technical Specifications

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Microsoft Windows Bluetooth Software

Supported Link Topology

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Certifications

Power Management ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL. CSA, and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Laver Ping LE Dual Mode LE Link Laver

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection-Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. Maximum output power may vary by country according to local regulations.
- 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Wireless LAN IEEE 802.11a

Technical Specifications

IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability Features Wi-Fi 6 technology

Frequency Band •802.11b/g/n/ax

2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz"

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) •802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ •IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

•WPA2 certification •WPA3 certification •IEEE 802.11i

•WAPI

Network Ad-hoc (Peer to Peer)

Architecture Models Infrastructure (Access Point Required)

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•802.11g:+17.5dBm minimum •802.11a:+18.5dBm minimum

•802.11n HT20(2.4GHz): +15.5dBm minimum
•802.11n HT40(2.4GHz): +14.5dBm minimum
•802.11n HT20(5GHz): +15.5dBm minimum
•802.11n HT40(5GHz): +14.5dBm minimum
•802.11ac VHT80(5GHz): +11.5dBm minimum
•802.11ac VHT160(5GHz): +11.5dBm minimum
•802.11ax HT40(2.4GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W



Technical Specifications

Receive mode 1.6 W

Idle mode (PSP)180 mW(WLAN Associated)
Idle mode50 mW (WLAN unassociated)

Connected Standby 10mW Radio disabled8 mW"

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ •802.11b, 1Mbps: 93.5dBm maximum

•802.11b, 11Mbps: 84dBm maximum •802.11a/g, 6Mbps: 86dBm maximum •802.11a/g, 54Mbps: 72dBm maximum •802.11n, MCS07: 67dBm maximum •802.11n, MCS15: 64dBm maximum •802.11ac, MCS0: 84dBm maximum •802.11ac, MCS9: 59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

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2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (–10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

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LED Activity LED Amber – Radio OFF; LED Off – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

DLE. 0"39 (2 MI12/CII)

Data Rates and Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput** BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric

(3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW



Technical Specifications

Supported Link

Bluetooth Software Microsoft Windows Bluetooth Software

Topology

Power Management Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826 Certifications

Certifications

Low Voltage Directive IEC950

UL. CSA. and CE Mark

Bluetooth Profiles Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Laver Ping

LE Dual Mode LE Link Laver

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Laver Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. Maximum output power may vary by country according to local regulations.
- 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Intel® XMM™ 7360 LTE-Advanced

Technology/Operating FDD LTE:

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4),

850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12), 700

(Band 13)

700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band 21), 850

(Band 26)

700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz

TDD LTE:

2600 (Band 38), 1900 (Band 39) 2300 (Band 40), 2500 (Band 41) MHz

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900 (Band 8)

MHz

Wireless protocol standards

bands

3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-B and LTO)



Technical Specifications

GPS bands GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 ±

2.046 MHz

Maximum data rates LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.



Technical Specifications

Qualcomm® Snapdragon™ X55 5G Cat 20 ¹ Technology/ Operating bands WCDMA/HSDPA/HSUPA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 9: 1750 to 1785 MHz(UL), 1845to 1880 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL). 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL). 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 32: 1452 to 1496 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL) 5GNR Sub 6GHZ n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) n41: 2496 to 2690 MHz (UL/DL) n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL) n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)



Technical Specifications

Wireless protocol Standards 5GNR Air Interface

standards l 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput – 4 × 4 MIMO

across 5x CA

200 Mbps uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA

R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands GPS: L1 (1575.42MHz); L5 (1176MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz)

Galileo E1 (1575.42); E5a (1176MHz)

Maximum data rates 5G sub 6G: 3.8 Gbps

LTE: ue-CategoryDL 20, (DL : 2 Gbps) ue-CategoryUL 13 , (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

HSPA+: 23.5 dBm
Maximum power consumption 5G Sub 6: 2500 mA

LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 8 g

Dimensions

(Length x Width x Thickness) 42 mm × 30 mm × 2.6 mm

1. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

NXP NPC300 Near

Dimensions (L x W x H)

Module 17 mm by 10 mm by 2.0 mm

Field Communication Module

> Chipset NPC300 System interface I²C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD) Mode¹ ISO/IEC 14443 A



Technical Specifications

ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-

VICC) Mode¹

ISO/IEC 14443 A

ISO/IEC 14443 B and B'

MIFARE FeliCa

13.56 MHz **Frequency**

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating temperature -25°C to 80°C Storage temperature -25°C to 125°C **Humidity** 10-90% operating

5-95% non-operating

Supply Operating voltage 2.7 to 5.5 Volts I/O Voltage 1.8V or 3.3V

Power Consumption (Booster enable, **VBAT= 3.3V.** VCC_BOOST = 5V)

> Mode Power Consumption, Typical (2)

Plling 710.93 mW Detected Test Tag Type 1 152.09 mW Detected Test Tag Type 2 341.26 mW Detected Test Tag Type 3 383.76 mW Detected Test Tag Type 4 312.26 mW

Antenna Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is external

to module.

Built-in Tile™ module1

Bluetooth Core Specification v5.0 **Bluetooth Specification**

Frequency Band 2400 to 2483.5 MHz

Number of Available

Channels

0-39 Channels with 2MHz bandwidth at each channel

Data Rate BLE: 1 Mbps data rate **Transmit Power** Max TX power: 8dBm

Power Consumption "<0.1mW at idle mode (ready to be found)

Form Factor PCI-Express M.2 MiniCard **Dimensions** Type 3042: 30 x 42 x 2.3 mm

Weight Weight: 4.0g



Technical Specifications

Operating Voltage DC 3.135V \sim 3.6V, Typical 3.3V Temperature Operating: $-10^{\circ}\text{C} \sim +55^{\circ}\text{C}$ Non-operating: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

1. Tile is an optional feature that must be configured at the factory and requires Windows 10. Some features require optional subscription to Tile Premium.. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.



Technical Specifications

POWER

AC Adapter 65 Watt Smart Dimensions (H x W x D)

nPFC Standard Barrel 4.5mm Right Angle 1.8m

Weight

107.0x47.0x30.0mm

unit: 250g +/- 10g

Not including power cord. Power cord varies by country

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output power 65 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications ECE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC. NOM-1 NYCE.* MTBF - over 200.000 hours at 25°C

ambient condition.

AC Adapter 45 Watt Smart Dimensions (H x W x D) 95.03

nPFC Standard Barrel 4.5mm Right Angle 1.8m

Weight

95.0x40.0x26.5mm

unit: 200g +/- 10g

Not including power cord. Power cord varies by country

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0 A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)



Technical Specifications

Humidity 20% to 95%

Storage Humidity 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong **Dimensions (H x W x D)** 95x45x26.8mm

Weight unit: 200g +/- 10g

Not including power cord. Power cord varies by country

Input Input Efficiency 87.74 % at 115 Vac and 88.4 % at 230 Vac

Input frequency range 47 ~ 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output Output power 45 W

DC output 19.5 V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0 A

Connector 4.5 mm Barrel Type

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating -4°F to 185°F (-20°to 85°C)

(storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95%

Storage Humidity 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5mm New EM **Dimensions (H x W x D)** 102x55x30mm

Weight 270g +/- 10g

Not including power cord. Power cord varies by country

Input Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230 Vac

Input frequency range 47 to 63 Hz

Input AC current Max. 1.7 A at 90 Vac

Output Output Power 65 W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <11.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable

cords

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating -4°F to 185°F (-20°to 85°C)

(storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions (H x W x D)
Standard USB Type-C
Straight 1.8m
Weight

Dimensions (H x W x D) 90.0x51x28.5mm

Weight unit: 250g +/- 10g

Not including power cord. Power cord varies by country

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

47 to 63 Hz

Input frequency range 47 to 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65 W

DC output 5V/9V/12V/15V/20V **Hold-up time** 5 msec at 115 VAC input

Output current limit 8.0A MAXIMUM

Connector USB Type-C

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature



Technical Specifications

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, ul62368. Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022

Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

MTBF - over 200.000 hours at 25°C ambient condition."

AC Adapter 65 Watt nPFC Dimensions (H x W x D)

Slim USB Type-C Straight 1.8m

Weight

unit: 220g +/- 10g

88x53.5x21mm

Not including power cord. Power cord varies by country

Input **Input Efficiency**

> 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

81.5% min at 115 Vac/ 230Vac @ 5V/3A

Input frequency range 47 to 63Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output **Output Power**

> DC output 5V/9V/12V/15V/20V Hold-up time 5 msec at 115 VAC input

Output current limit <8.0A

Connector **USB Type C**

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16.400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety CE Mark - full compliance with LVD and EMC directives

Certifications Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,

SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B. CISPR22 Class B. CCC. NOM-1 NYCE.

MTBF - over 100.000 hours at 25°C ambient condition.

HP 3 Cell 53 Wh Long Life Dimensions (H x W x D) -PL Fast Charge

267.3x59.75x7.5mm

Weight 210a±10a

Not including power cord. Power cord varies by country

Cells/Type 3cell Lithium-Ion Polymer cell / 645180



Technical Specifications

Voltage 11.55V
Amp-hour capacity 4590mAh
Watt-hour capacity¹ 53Wh

Operating (Charging) 32° to 113° F (0° to 45° C)
Operating (Discharging) 14° to 122° F (-10° to 60° C)

Fuel Gauge LED NA
Optional Travel Battery No

Available

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

FINGERPRINTREADER

Model
Synaptics Validity VFS7552 touch sensor
Mobile Voltage Operation
3.0V to 3.6V
Operating Temperature
14° – 167°F (-10°-75°C)
Current Consumption Image
36mA peak
Low Latency Wait For Finger
950 uA
Capture Rate
30 cm/sec
ESD Resistance
IEC 61000-4-2 4B (+15KV)

Detection Matrix 200*1 (Plus another secondary line) / 508 dpi / 10mm sensor area

FRR (False Reject Rate) / FAR (False Acceptance Rate) FRR ~ 1% @ 1:50K FAR



Technical Specifications

ENVIRONMENTAL DATA

Sustainable Impact Specifications

- Bulk packaging available
- Low halogen1
- Ocean-Bound Plastic in speaker enclosure²
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable³
- 35% post-consumer recycled plastic4
- 1. External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 2. Percentage of ocean-bound plastic contained in each component varies by product
- 3. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- 4. Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.

Country of Origin

China

Туре	Description	Part Number	
Cases	HP Prelude Pro Top Load	1X645AA	
	HP Prelude Pro Backpack	1X644AA	
	HP Business Backpack (17.3")	2SC67AA	
	HP Business Case (15.6")	2SC66AA	
	HP Business Slim Top Load (14.1")	2SC65AA	
	HP 14.1 Business Sleeve	2UW01AA	
	HP 13.3 Business Sleeve	2UW00AA	
Docking	HP Thunderbolt Dock 120W G2	2UK37AA	
	HP Thunderbolt Dock 230W G2	2UK38AA	
	HP TB Dock w/ Combo Cable (230W)	3TR87AA	
	HP TB Dock Audio Module	3AQ21AA	
	HP TB Dock 230W G2 Cable	3XB95AA	
	HP TB Dock 120W G2 cable	3XB94AA	
	HP TB Dock G2 combo cable	3XB96AA	
	HP USB Type-C Mini Dock	1PM64AA	
	HP USB Type-C Dock G5	5TW10AA	
	HP USB Type-C /A Universal Dock G2	5TW13AA	
Input / Output	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA	



Technical Specifications

HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
HP Wireless Premium Keyboard	Z9N41AA
HP USB Essential Keyboard and Mouse	H6L29AA
HP Wireless Collaboration Keyboard	Z9N39AA
HP 935 Creator Wireless Mouse	1D0K8AA
HP 635 Multi-Device Wireless Mouse	1D0K2AA
HP Comfort Grip Wireless Mouse	H2L63AA
HP X4000b Bluetooth Mouse	H3T50AA
HP Wired Desktop 320M Mouse	9VA80AA
HP USB Travel Mouse	G1K28AA
HP Bluetooth Travel Mouse	6SP30AA
HP Wireless Premium Mouse	1JR31AA
HP USB Premium Mouse	1JR32AA
HP Elite Presenter Mouse	2CE30AA
HP Stereo 3.5mm Headset	T1A66AA
HP Stereo USB Headset	T1A67AA
HP UC Wireless Mono Headset	W3K08AA
HP UC Wireless Duo Headset	W3K09AA
HP USB Type-C to USB-A Hub	Z6A00AA
HP USB Type-C to DP	N9K78AA
HP USB Type-C to VGA	N9K76AA
HP HDMI to VGA	H4F02AA
HP USB Type-C to HDMI 2.0 Adapter	1WC36AA
HP USB Type-C to RJ45 Adapter	V7W66AA
HP USB Type-C Travel Hub G2	7PJ38AA
HP Elite USB Type-C Hub	4WX89AA

Power HP 65W Slim AC Adapter H6Y82AA

HP 45W Smart AC Adapter H6Y88AA HP 65W Smart AC Adapter H6Y89AA HP 45W 2-prong 4.5 mm DC jack AC Adapter L6F60AA#ABJ HP 45W USB-C Power Adapter 1HE07AA HP 65W USB-C Power Adapter 1HE08AA 65W USB Type-C® Slim Power Adapter 3PN48AA **HP Notebook Power Bank** N9F71AA **HP USB-C Essential Power Bank** 3TB55AA

Storage HP USB External DVDRW Drive F2B56AA

HP 256GB PCI-e 3x4 NVMe M.2 SSD

TBT
HP 512GB PCI-e 3x4 NVMe M.2 SSD

TBT

Security HP Nano Keyed Cable Lock 1AJ39AA

HP Sure Key Cable Lock 6UW42AA



HP EliteBook x360 830 G8 Notebook PC

QuickSpecs

Technical Specifications



Summary of changes

Date of change:	Version History:		Description of change:
January 29, 20201	V1 to V2	Update	USB Ports
February 4, 2021	V2 to V3	Added	Processors, WPA3 certification
February 8, 2021	V3 to V4	Update	Smart Card Reader
February 10, 2021	V4 to V5	Update	Environmental Data

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